

**TOREX SEMICONDUCTOR LTD.**  
Quality Assurance Dept.

## Composition Table

Product(Pb-free): XC61FxxxxxMR-G

Typical Mass: 14 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.528	Silicon	37700	7440-21-3
Leadframe	3.553	Copper	253800	7440-50-8
	0.011	Tin	800	7440-31-5
	0.006	Zinc	400	7440-66-6
	0.011	Chromium	800	7440-47-3
	0.159	Silver	11300	7440-22-4
Die attach	0.040	Silver	2800	7440-22-4
	0.007	Epoxy	500	—
Bonding wire	0.030	Gold	2100	7440-57-5
Resin	7.687	Silica	549000	60676-86-0
	0.718	Epoxy Resin	51300	—
	0.614	Phenol Resin	43900	—
	0.436	Metal hydroxide	31200	—
Plating	0.200	Tin	14300	7440-31-5

\* The component composition is based on the information provided by raw material vender.

\* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

\* Any indication "-" in CAS number means "confidential."